

Fujitsu Announces New WiMax Chip

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Fujitsu Microelectronics America is announcing the company's first mobile silicon on chip WiMax product at Interop in Las Vegas.

The baseband product, affectionately known as the MB86K21 802.16e, is designed to show significant performance improvements over competing products in the WiMax chip market. The company will start shipping samples in August.

The new device meets all requirements for the WiMax Forum Wave 2 mobile device certification. It supports 5 and 10 MHz channel bandwidths, has a variety of adaptive modulations modes and has security support built in. The product will support USB 2.0 and Card Bus / PCI host interface support.

The first shipments of the new chip are expected to be in Asia, with U.S. shipments to follow. Fujitsu will offer a Systems Design Kit and a PC Card Reference Platform Delivery Kit so that customers can move into production quickly. The SDK can use a variety of RF platforms to meet various frequency requirements globally.

The company has successfully completed industry wide plugfests to validate its operation. Pricing has not been announced.

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